Bootmode selection can be hard wired if required modes are known.
Place Near U6 as close to U6 as possible

Minimize Trace Length

U6 MUST BE on TOP (OUTER, FREE-AIR) side of board!!!!

NOTE:
For CENELEC A band use 680pf for C10 and C11
For CENELEC B/C band use 560pf for C10 and 270pf for C11.

Optional Components:
necessary for G1 only, use 2700 pF 6V for C61 and a 510R 5% for R41

Optional Components:
necessary for G1 only, use 2700 pF 6V for C62 and a 510R 5% for R42

NOTE:
For CENELEC A band use 680pf for C10 and C11
For CENELEC B/C band use 560pf for C10 and 270pf for C11.
NOTE: Several components on this page have been removed or changed in the BOM.
OPTIONAL: Heatsink is not needed.

OPTIONAL: to source VDD with the on-chip LDO, do not populate R43 and place a 10k resistor on R27. Additionally, the optional components below are not needed.

OPTIONAL: For reduced power consumption use a DC/DC converter instead of the On-Chip Linear Supply. Note: Follow Layout Procedures described in TPS62240 Datasheet.
Notes/Revision Information

01 - Title / Notes
02 - Coupling Circuit
03 - USB JTAG/UART
04 - System Power
05 - Connectors
HIGH VOLTAGE!
VDDS decoupling capacitors

VDDR decoupling capacitors

Place L331 and C331 close to pin 33.
Low inductance ground for C331

*VDDS Decoupling Capacitors*

- Pin 22
- Pin 44
- Pin 13
- Pin 34

*VDDR Decoupling Capacitors*

- Pin 48
- Pin 45

Mount either R11 or R12 To select SMA or PCB ant.

**EM connector 1**

**EM connector 2**

Title: CC13xxEM-7XD-7793, main

Drawn: a0132595

Checked: <Check name>

Size: A3

Rev: 1.3.3

Page: 1 of 2

Date: Tuesday, August 25, 2015
R 1.0.0
---Initial release revision

R 1.0.1
L3 -> Changed from LQG to LQW
L4 -> Changed from LQG to LQW

R 1.1.0
- New CC13xx symbol with different DIO to pin mapping
- New Crystal (9 pF, from 7 pF. But 9 pF has been assembled on previous EMs).
- New reference numbers on components.

R 1.2.0
- Updating RF filter for better harmonic suppression.
- Remove test point on RXTX pin.

R 1.3.0
- For IC3:
  - C15 33pF -> 100pF
  - L12, L21 8.2nH -> 7.5nH
  - C13 4.7nH -> 6.2nH
  - C14 2.2nH -> 3.3nH

R 1.3.1
L331 10uH -> 6.8uH

R 1.3.2
C341 10uF -> 22uF

R 1.3.3
C331 10uF -> 22uF
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